



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



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企业QQ二维码

Product Summary

BV_{DSS}	$R_{DS(ON)}$	I_D $T_C = +25^\circ C$
100V	32m Ω @ $V_{GS} = 10V$	33A
	50m Ω @ $V_{GS} = 4.5V$	26A

Features

- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection

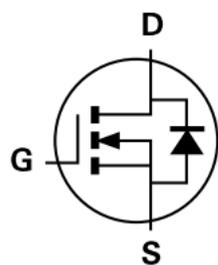
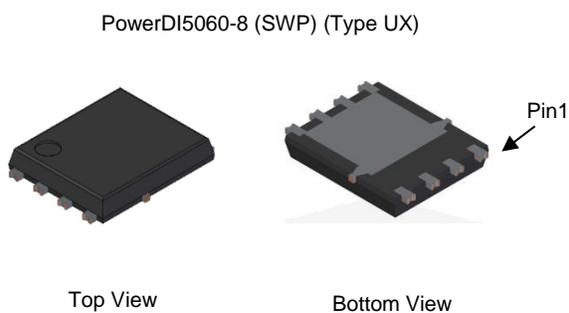
Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP, and is ideal for use in:

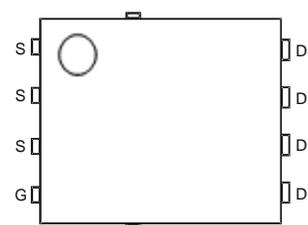
- Synchronous rectifiers
- Backlighting
- Power management functions
- DC-DC converters

Mechanical Data

- Package: PowerDI[®]5060-8 (SWP) (Type UX)
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish — Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 
- Weight: 0.097 grams (Approximate)



Internal Schematic



Top View
Pin Configuration

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current, $V_{GS} = 10\text{V}$ (Note 5)	I_D	$T_C = +25^\circ\text{C}$	33
		$T_C = +100^\circ\text{C}$	23
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)	I_{DM}	132	A
Maximum Continuous Body Diode Forward Current (Note 5)	I_S	33	A
Pulsed Body Diode Forward Current (10 μs Pulse, Duty Cycle = 1%)	I_{SM}	132	A
Avalanche Current, $L = 0.3\text{mH}$ (Note 6)	I_{AS}	13	A
Avalanche Energy, $L = 0.3\text{mH}$ (Note 6)	E_{AS}	25.3	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 7)	P_D	3.4	W
Thermal Resistance, Junction to Ambient (Note 7)			
Total Power Dissipation (Note 5)	P_D	68	W
Thermal Resistance, Junction to Case (Note 5)			
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +175	$^\circ\text{C}$

- Notes:
5. Thermal resistance from junction to soldering point (on the exposed drain pad).
 6. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.
 7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	V _{GS} = 0V, I _D = 1mA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 80V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	1.3	—	2.5	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	22	32	mΩ	V _{GS} = 10V, I _D = 5A
		—	32	50		V _{GS} = 4.5V, I _D = 4.5A
Diode Forward Voltage	V _{SD}	—	0.8	1	V	V _{GS} = 0V, I _S = 5A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	683	—	pF	V _{DS} = 50V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	165	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	6.9	—	pF	
Gate Resistance	R _g	—	1.2	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	6.3	—	nC	V _{DS} = 50V, I _D = 6A
Total Gate Charge (V _{GS} = 10V)	Q _g	—	11.9	—	nC	
Gate-Source Charge	Q _{gs}	—	2.0	—	nC	
Gate-Drain Charge	Q _{gd}	—	3.1	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	4.1	—	ns	V _{DS} = 50V, R _L = 5.85Ω V _{GS} = 10V, R _g = 3Ω
Turn-On Rise Time	t _r	—	4.5	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	12.5	—	ns	
Turn-Off Fall Time	t _f	—	9.3	—	ns	
Reverse Recovery Time	t _{RR}	—	31.5	—	ns	I _F = 6A, di/dt = 500A/μs
Reverse Recovery Charge	Q _{RR}	—	94.6	—	nC	

Notes: 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.

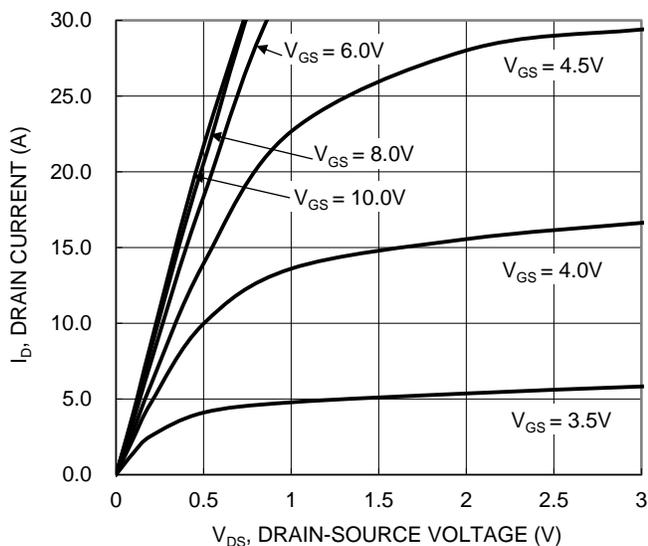


Figure 1. Typical Output Characteristic

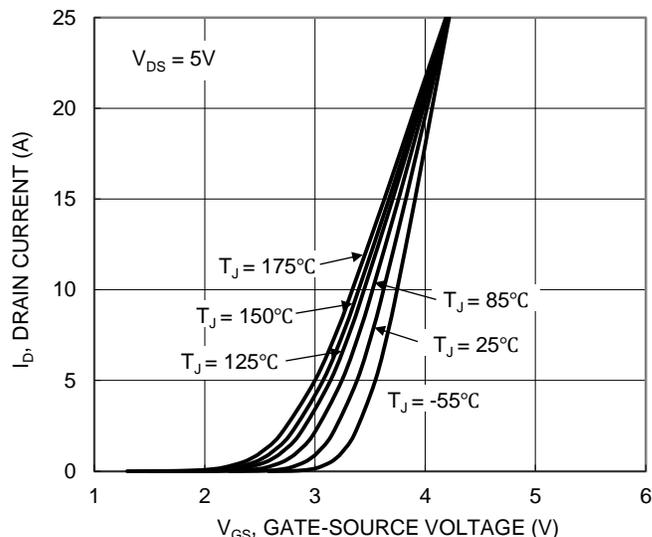


Figure 2. Typical Transfer Characteristic

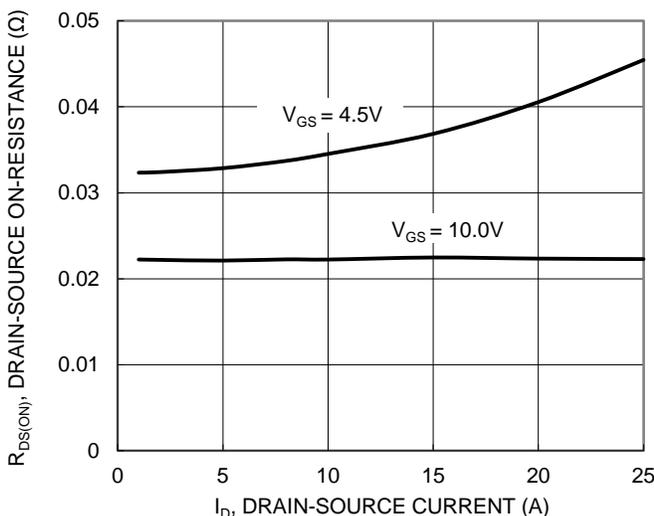


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

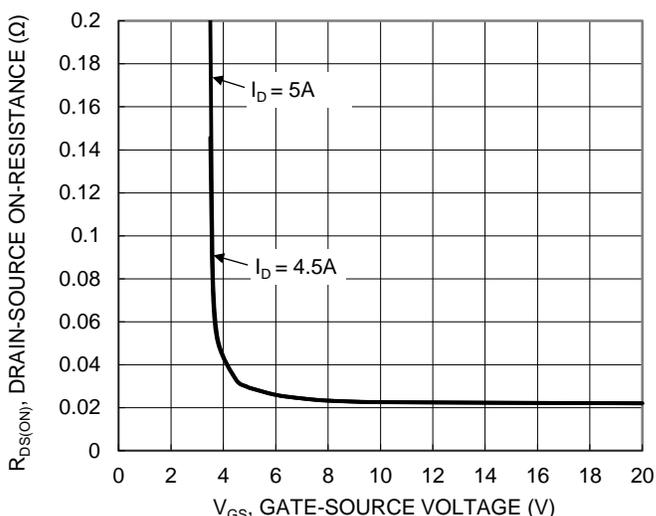


Figure 4. Typical Transfer Characteristic

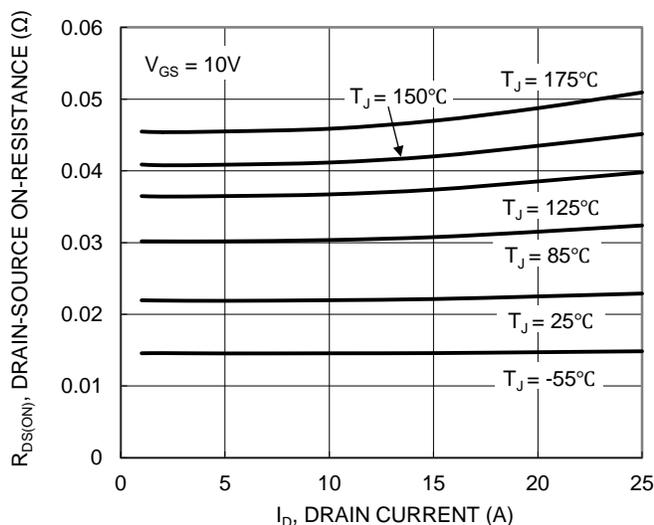


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

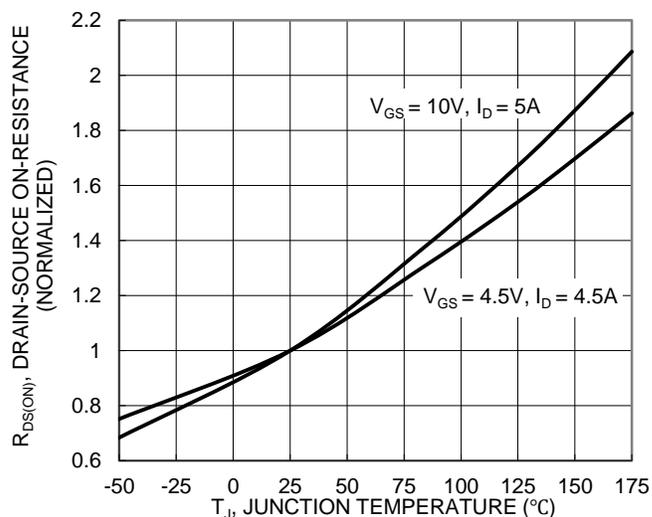


Figure 6. On-Resistance Variation with Junction Temperature

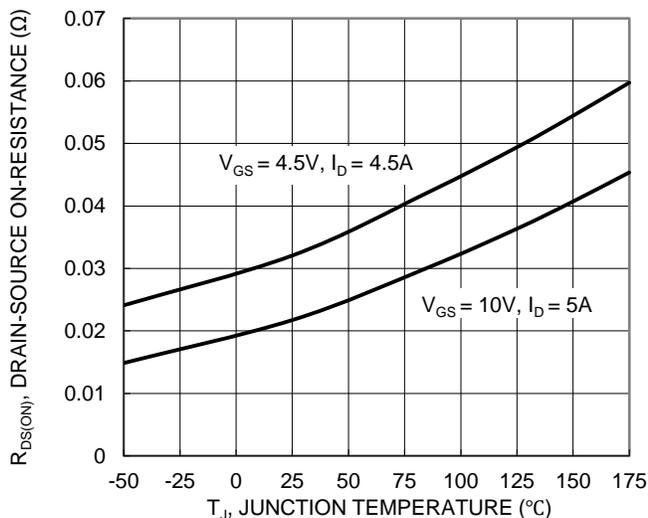


Figure 7. On-Resistance Variation with Junction Temperature

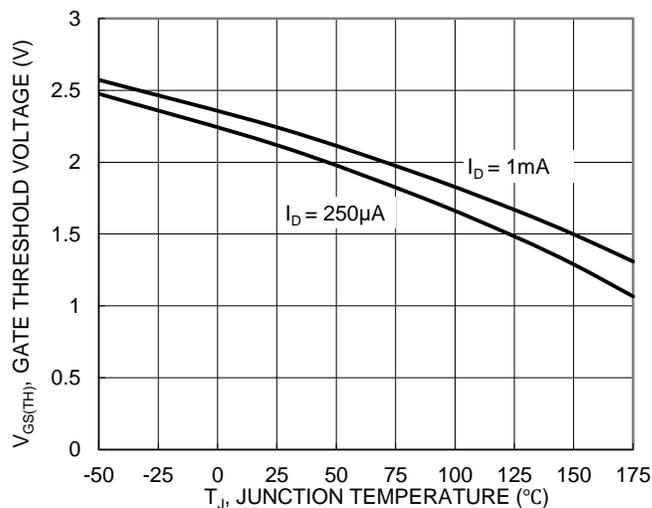


Figure 8. Gate Threshold Variation vs. Junction Temperature

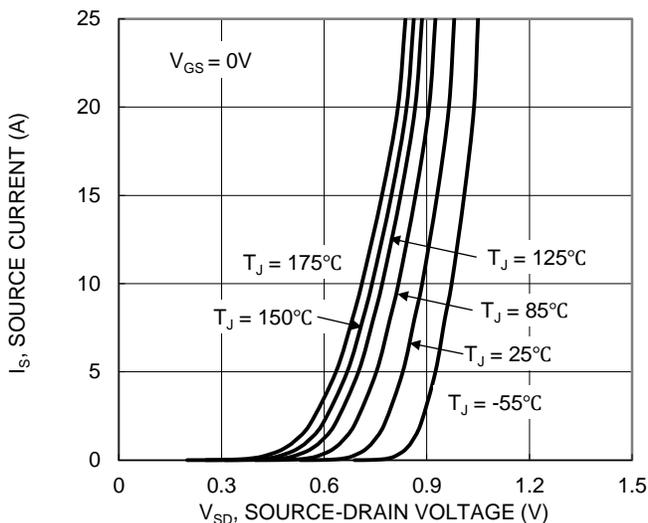


Figure 9. Diode Forward Voltage vs. Current

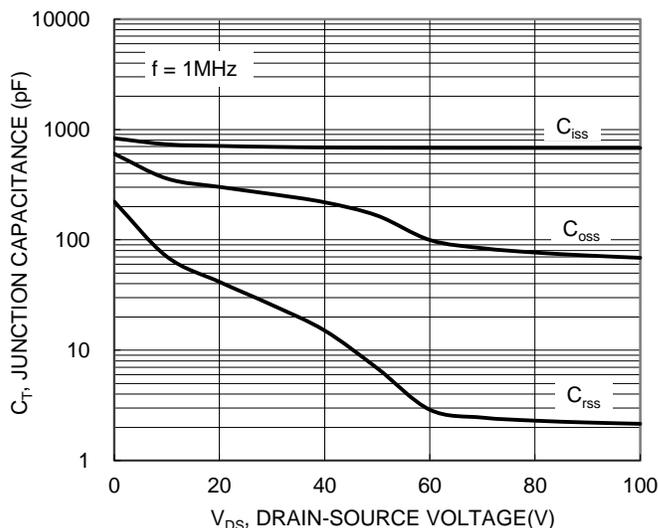


Figure 10. Typical Junction Capacitance

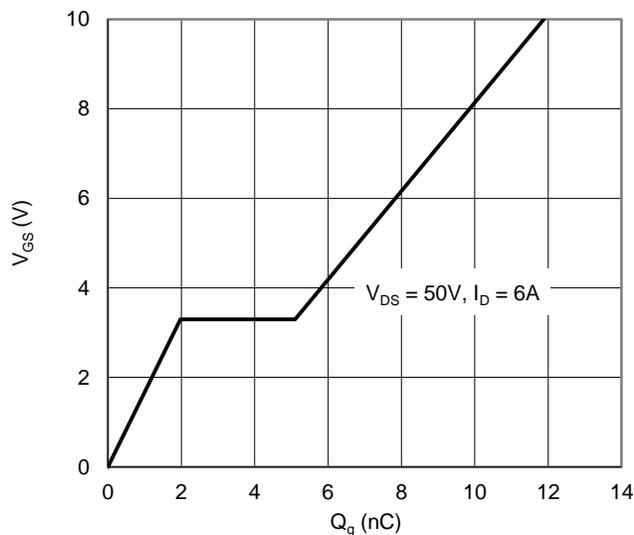


Figure 11. Gate Charge

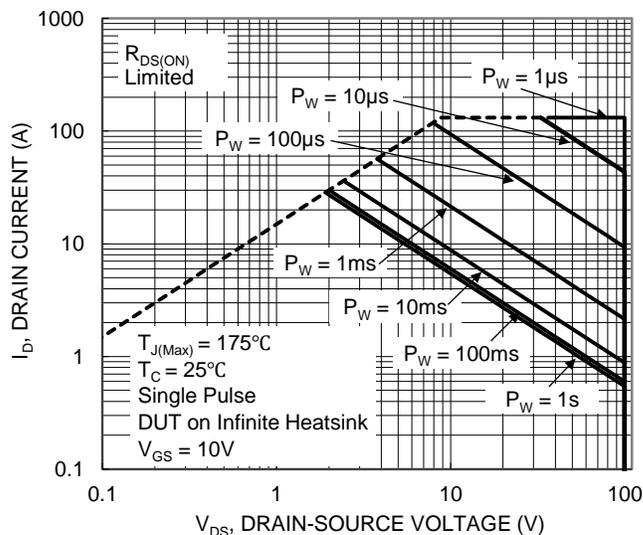


Figure 12. SOA, Safe Operation Area

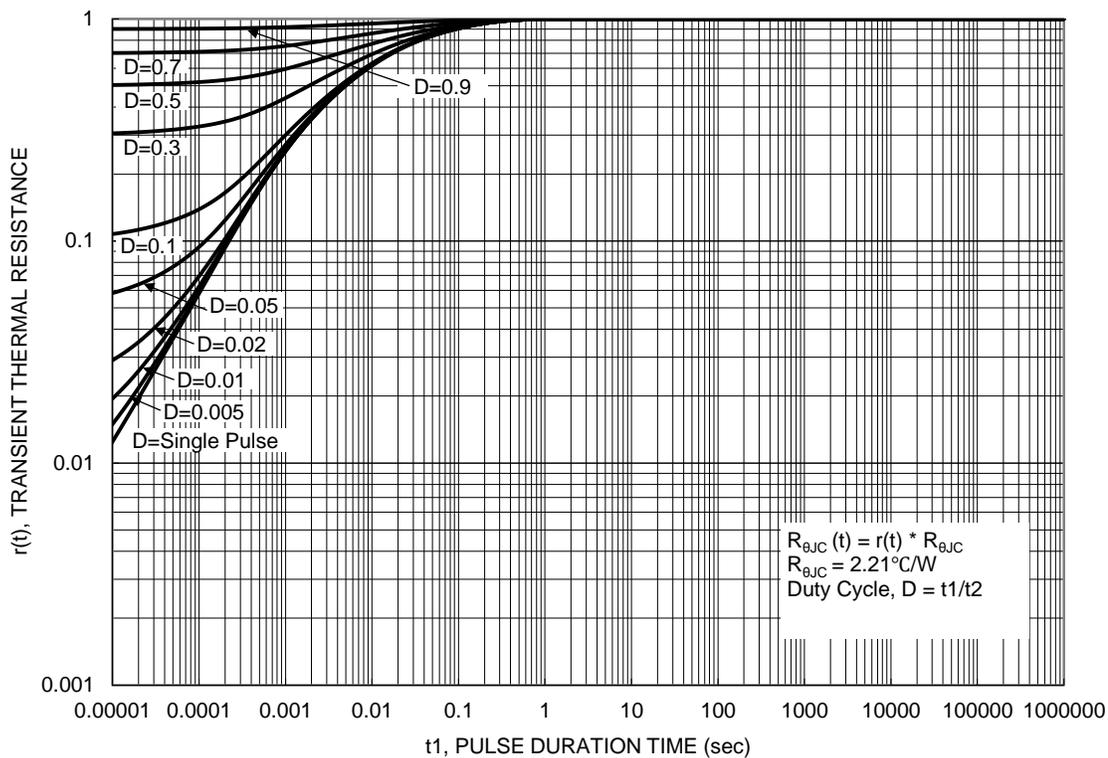
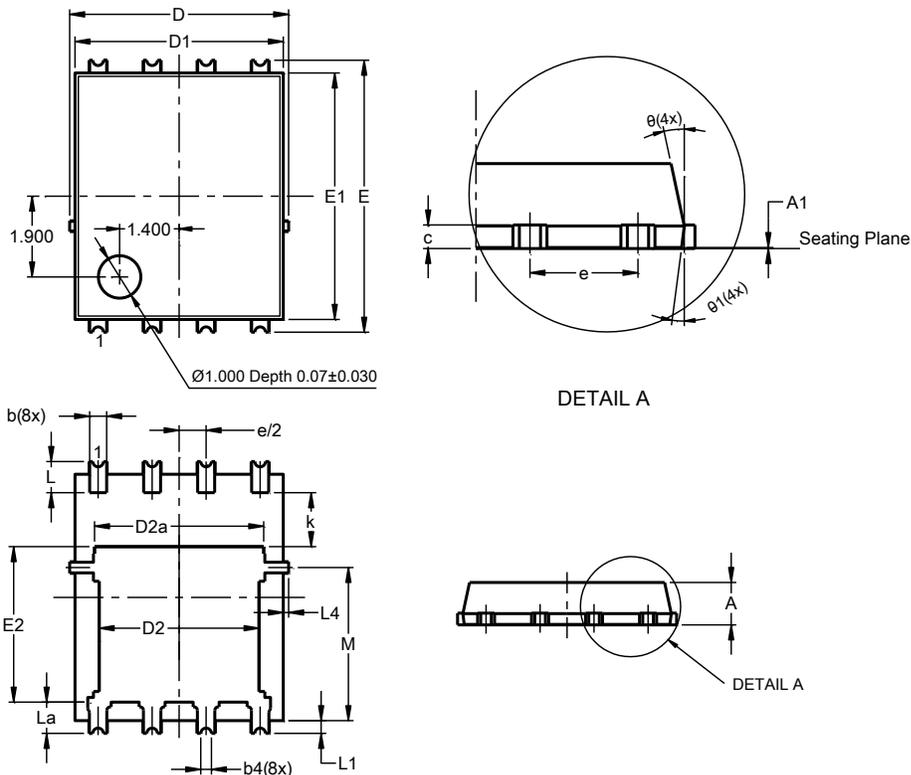


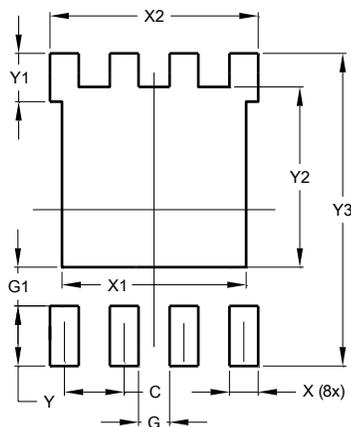
Figure 13. Transient Thermal Resistance

Package Outline Dimensions

PowerDI5060-8 (SWP) (Type UX)


PowerDI5060-8 (SWP) (Type UX)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0	0.05	--
b	0.30	0.50	0.41
b2	0.20	0.35	0.25
b4	0.25REF		
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.56	3.96	3.76
D2a	3.78	4.18	3.98
E	6.40 BSC		
E1	5.60	6.00	5.80
E2	3.46	3.86	3.66
E2a	4.195	4.595	4.395
e	1.27BSC		
k	1.05	--	--
L	0.635	0.835	0.735
La	0.635	0.835	0.735
L1	0.200	0.400	0.300
L1a	0.050REF		
L4	0.025	0.225	0.125
M	3.205	4.005	3.605
theta	10°	12°	11°
theta1	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout

PowerDI5060-8 (SWP) (Type UX)


Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610